Overview
The purpose of this notification is to announce conversion of substrate material changed from BT to ABF build-up for select Virtex®-II Pro FPGA device/package. There is no change to the form, fit, function or reliability with this change.

Description
For the below affected products, substrate materials will be converted from BT to ABF build-up. The reason for the change is the phase out of UV laser equipment support at substrate supplier. To ensure continuity of supply for flip chip products, BT will be replaced by ABF since UV laser is not required to form via’s with ABF material. The ABF materials set has been already qualified and in production for other Virtex-II Pro FPGA, Virtex®-4 FPGA and Virtex®-5 FPGA products.

Products Affected
This change affects all speed, package, and temperature variations of the commercial (C) and industrial (I) grade devices. All SCD parts derived from base part are also affected. Affected part numbers are included in the following table(s):

<table>
<thead>
<tr>
<th>Xilinx Product</th>
<th>Package</th>
<th>Change Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>XC2VP70</td>
<td>FF(G)1704</td>
<td>Build-up materials set change from BT to ABF</td>
</tr>
<tr>
<td>XC2VP100</td>
<td>FF(G)1704</td>
<td>Build-up materials set change from BT to ABF</td>
</tr>
</tbody>
</table>

Note: All SCD parts are also affected.

Key Dates and Ordering Information
Xilinx will begin to cross-ship production using BT and ABF substrate materials on or after 90 days of PCN date.
Qualification Data

Qualification data & device reliability report for Virtex-II Pro FPGA devices is available in UG116. The extended qualification data related to this PCN is available in RPT141 located in ‘Additional Document’ section below.

Response

No response is required. For additional information or questions, please contact Xilinx Technical Support.

Important Notice: Xilinx Customer Notifications (XCNs, XDNs, and Quality Alerts) can be delivered via e-mail alerts sent by the MySupport website (http://www.xilinx.com/support). Register today and personalize your “MyAlerts” area to include Customer Notifications. Xilinx MySupport provides many benefits, including the ability to receive alerts for new and updated information about specific products, as well as alerts for other publications such as data sheets, errata, application notes, etc. For information on how to sign up, refer to Xilinx Answer Record 18683.

Additional Documentation

Qualification Report (RPT141)
https://secure.xilinx.com/webreg/clickthrough.do?cid=140202

Device Reliability Report (UG116):

Revision History

The following table shows the revision history for this document.

<table>
<thead>
<tr>
<th>Date</th>
<th>Version</th>
<th>Revision</th>
</tr>
</thead>
<tbody>
<tr>
<td>04/19/10</td>
<td>1.0</td>
<td>Initial release.</td>
</tr>
</tbody>
</table>

Notice of Disclaimer

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